MOSFET - N-Channel, SOT-23

300 mA, 20 V

MMBF0201NL, MVMBF0201NL

300 mAMPS – 20 VOLTS
$R_{DS(on)}$ = 1 Ω

These miniature surface mount MOSFETs low $R_{DS(on)}$ assure minimal power loss and conserve energy, making these devices ideal for use in small power management circuitry. Typical applications are dc–dc converters, power management in portable and battery–powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

Features

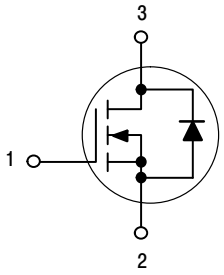
- Low $R_{DS(on)}$ Provides Higher Efficiency and Extends Battery Life
- Miniature SOT–23 Surface Mount Package Saves Board Space
- MVMBF Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable*
- These Devices are Pb–Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

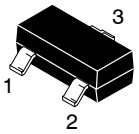
Rating	Symbol	Value	Unit
Drain–to–Source Voltage	V_{DSS}	20	Vdc
Gate–to–Source Voltage – Continuous	V_{GS}	± 20	Vdc
Drain Current – Continuous @ T_A = 25°C – Continuous @ T_A = 70°C – Pulsed Drain Current ($t_p \le 10$ μs)	 I_D I_D I_{DM}	 300 240 750	mAdc
Total Power Dissipation @ T_A = 25°C	P_D	225	mW
Operating and Storage Temperature Range	T_J, T_{stg}	– 55 to 150	°C
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	556	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8″ from case for 10 seconds	T_L	260	°C

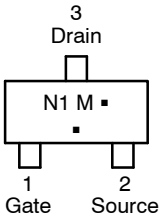
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

N–Channel



MARKING DIAGRAM AND PIN ASSIGNMENT





SOT–23
CASE 318
STYLE 21

N1 = Specific Device Code
M = Date Code*
▪ = Pb–Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
MMBF0201NLT1G	SOT–23 (Pb–Free)	3000 / Tape & Reel
MVMBF0201NLT1G*	SOT–23 (Pb–Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain−to−Source Breakdown Voltage (V_{GS} = 0 Vdc, I_D = 10 μA)		$V_{(BR)DSS}$	20	–	–	Vdc
Zero Gate Voltage Drain Current (V_{DS} = 16 Vdc, V_{GS} = 0 Vdc) (V_{DS} = 16 Vdc, V_{GS} = 0 Vdc, T_J = 125°C)		I_{DSS}	– –	– –	1.0 10	μAdc
Gate−Body Leakage Current (V_{GS} = ± 20 Vdc, V_{DS} = 0)		I_{GSS}	–	–	±100	nAdc
ON CHARACTERISTICS (Note 1)						
Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 250 μAdc)		$V_{GS(th)}$	1.0	1.7	2.4	Vdc
Static Drain−to−Source On−Resistance (V_{GS} = 10 Vdc, I_D = 300 mAdc) (V_{GS} = 4.5 Vdc, I_D = 100 mAdc)		$r_{DS(on)}$	– –	0.75 1.0	1.0 1.4	Ω
Forward Transconductance (V_{DS} = 10 Vdc, I_D = 200 mAdc)		g_{FS}	–	450	–	mMhos
DYNAMIC CHARACTERISTICS						
Input Capacitance	(V_{DS} = 5.0 V)	C_{iss}	–	45	–	pF
Output Capacitance	(V_{DS} = 5.0 V)	C_{oss}	–	25	–	
Transfer Capacitance	(V_{DG} = 5.0 V)	C_{rss}	–	5.0	–	
SWITCHING CHARACTERISTICS (Note 2)						
Turn−On Delay Time	(V_{DD} = 15 Vdc, I_D = 300 mAdc, R_L = 50 Ω)	$t_{d(on)}$	–	2.5	–	ns
Rise Time		t_r	–	2.5	–	
Turn−Off Delay Time		$t_{d(off)}$	–	15	–	
Fall Time		t_f	–	0.8	–	
Gate Charge (See Figure 5)		Q_T	–	1400	–	pC
SOURCE−DRAIN DIODE CHARACTERISTICS						
Continuous Current		I_S	–	–	0.3	A
Pulsed Current		I_{SM}	–	–	0.75	
Forward Voltage (Note 2)		V_{SD}	–	0.85	–	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
2. Switching characteristics are independent of operating junction temperature.

TYPICAL ELECTRICAL CHARACTERISTICS

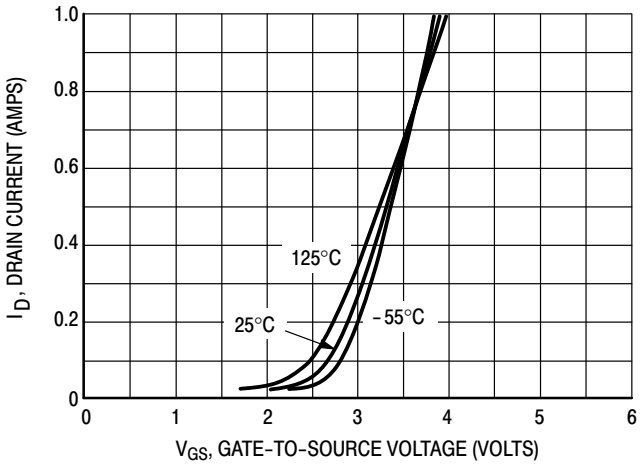


Figure 1. Transfer Characteristics

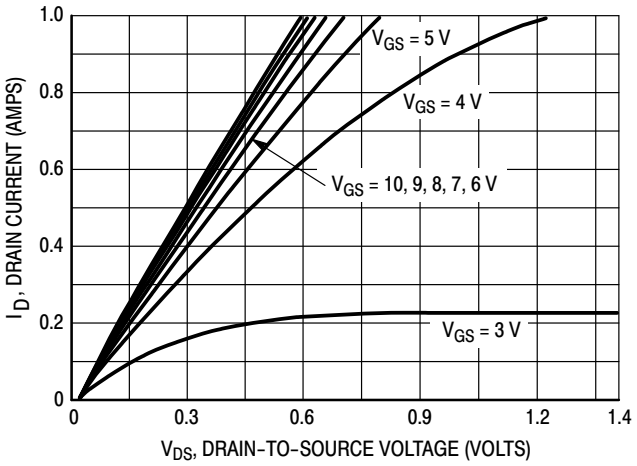


Figure 2. On−Region Characteristics

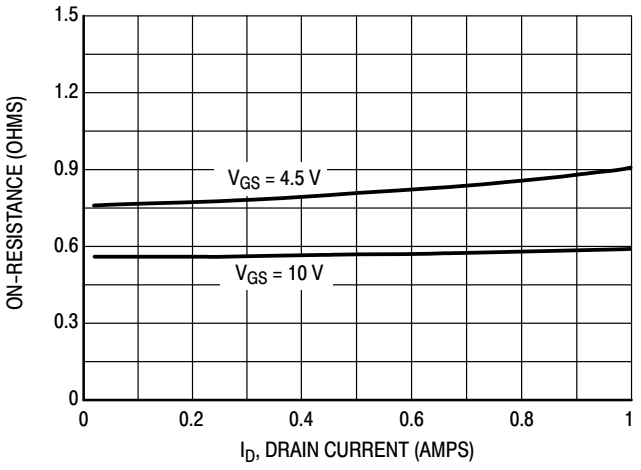


Figure 3. On−Resistance versus Drain Current

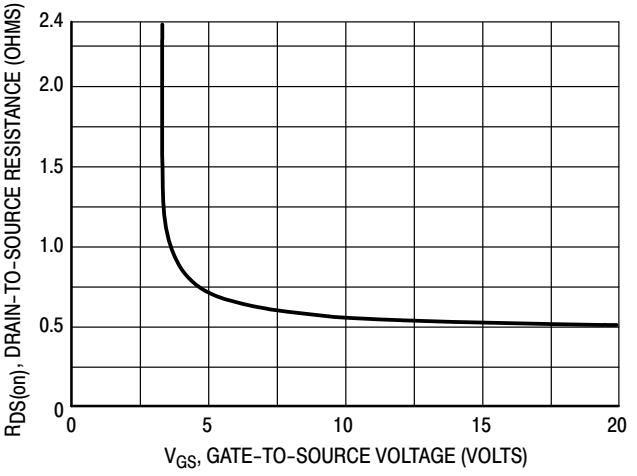


Figure 4. On−Resistance versus Gate−to−Source Voltage

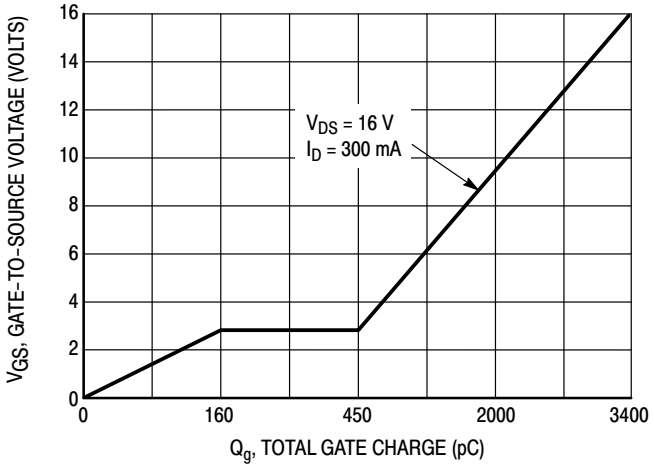


Figure 5. Gate Charge

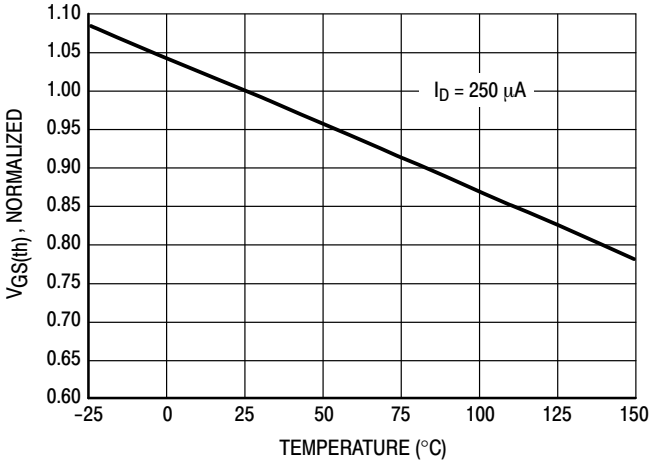


Figure 6. Threshold Voltage Variance Over Temperature

TYPICAL ELECTRICAL CHARACTERISTICS

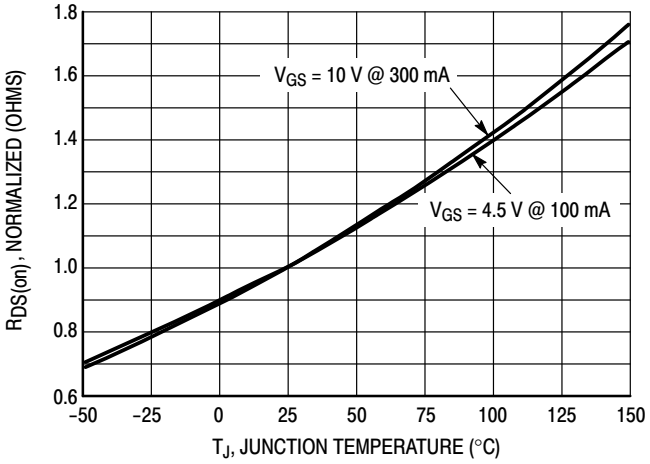


Figure 7. On−Resistance versus Junction Temperature

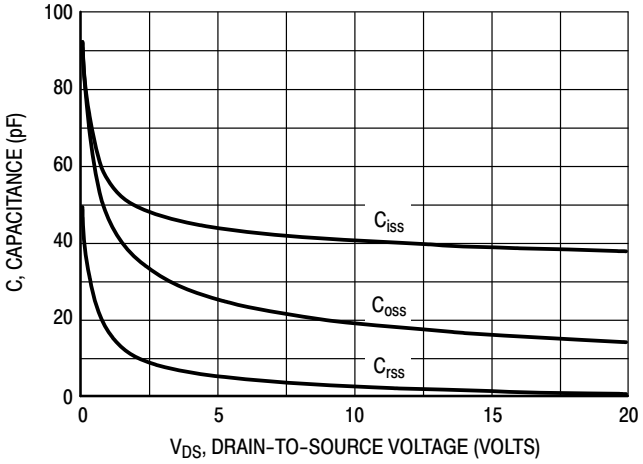


Figure 8. Capacitance

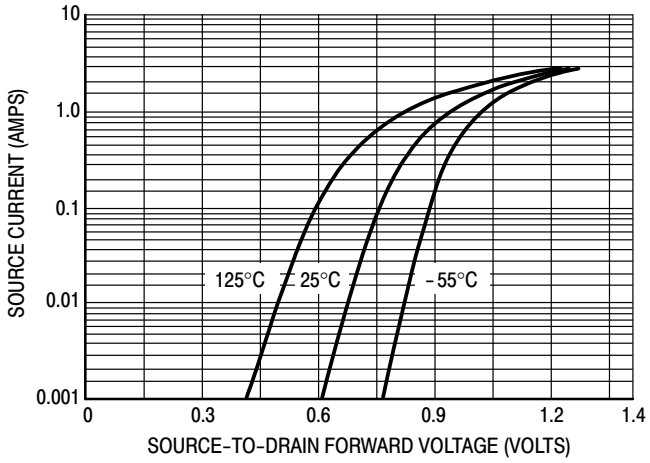
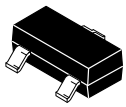


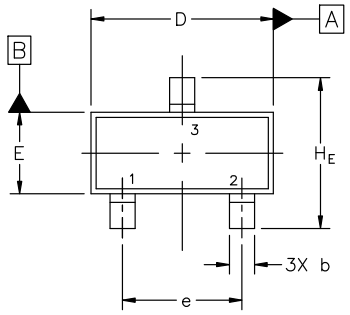
Figure 9. Source−to−Drain Forward Voltage versus Continuous Current (I_S)



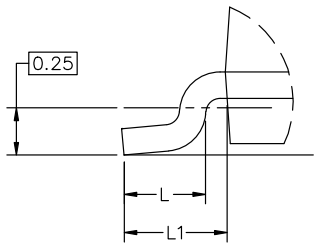
SCALE 4:1

SOT−23 (TO−236) 2.90x1.30x1.00 1.90P
CASE 318
ISSUE AU

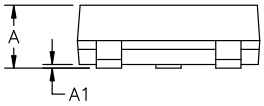
DATE 14 AUG 2024



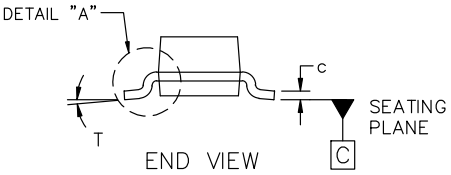
TOP VIEW



DETAIL "A"
Scale 3:1



SIDE VIEW

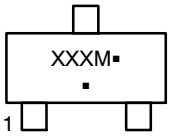


END VIEW

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.89	1.00	1.11
A1	0.01	0.06	0.10
b	0.37	0.44	0.50
c	0.08	0.14	0.20
D	2.80	2.90	3.04
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.43	0.55
L1	0.35	0.54	0.69
H_E	2.10	2.40	2.64
T	0°	−−−	10°

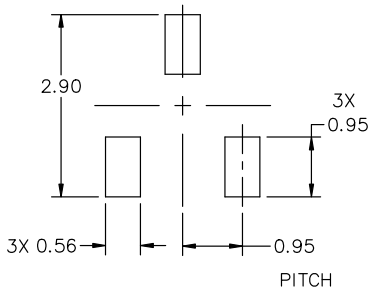
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

GENERIC
MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

DOCUMENT NUMBER:	**98ASB42226B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	**SOT−23 (TO−236) 2.90x1.30x1.00 1.90P**		**PAGE 1 OF 2**

SOT−23 (TO−236) 2.90x1.30x1.00 1.90P
CASE 318
ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE

STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE−ANODE

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE

STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE

STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE

STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE

STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE−ANODE

STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT

STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE

STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION

STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE

ADDITIONAL INFORMATION

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